



KE-1180 A/B

Shin-Etsu Silicones of America, Inc.
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Product Description

Shin-Etsu's KE-1180 A/B is a dual component, heat cure, high viscosity adhesive that will cure to form a tough, durable elastomer. KE-1180 A/B exhibits excellent unprimed adhesion to metals, plastics, glass, and ceramics.

Product Features

- Dual component
- Heat cured
- High viscosity

Typical Applications

- Form-in-place gasketing
- Sealing electronics

Typical Properties

Type	Adhesive/Sealant
Cure Type	Addition
One/Two Component	Two
Color	Pale yellow
Density @ 23C (g/cm ³)	1.07
Viscosity A (Pa·s)	158.00
Viscosity B (Pa·s)	57.00
Viscosity Mixed (Pa·s)	100.00
Mix Ratio by weight	100:100
Cure Conditions	1hr @ 80C
Tack Free Time (min)	360
Working Time	6 Hours
Shore A Hardness	20
Tensile Strength (MPa)	2.70
% Elongation	580
Shear Strength (MPa)	2.40
Usable Temperature Range (C)	-40 to +180

Note: Values are not for specification purposes.

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